Top Marking Change for UltraScale+ Defense-grade "XQ" Products

XCN18016 (v1.0) May 28, 2018 **Product Change Notice**

Overview

The purpose of this notification is to advise customers of top marking changes for Xilinx® UltraScale+™ Defense-grade "XQ" devices. There are no changes to fit, form, function, or reliability.

Description

Xilinx will be simplifying the topside marking for all Xilinx UltraScale+ Defense-grade "XQ" devices. All topside marking will be removed with the exception of Xilinx logo, 2D barcode, and country of origin. Device and package information will be accessed through the Xilinx 2D barcode application (refer to AR# 67513). This will allow much improved device-level traceability and security.

The 2D barcode contains a unique serial number that must be scanned using a camera based application to determine the serial number. The device and package information that were previously found on the top marking can only be retrieved using the unique serial number through an internet based application either on a mobile device or through a web browser using a portal (refer to XTP424 or XCN16014 for details). Scanning the existing License Plate Number (LPN) provided on the inner box and bag label will allow access to all device information and codes contained within a specific bag or box using the same portal.

Products Affected

This change affects all package, speed, and temperature grade variations for Xilinx UltraScale+ Defense-grade "XQ" devices. All associated specification control document (SCD) devices are also affected. Xilinx UltraScale+ Defense-grade "XQ" devices not yet in production will only ship with the new simplified top marking.

Key Dates and Ordering Information

Xilinx will begin shipping devices with new top marking starting August 27, 2018. Products with current top marking as shown in Table 1, 2 and 3, will cross ship until existing inventory is depleted.

Table 1: **UltraScale+ Zynq® MPSoC XQ Devices-Packages**

Device	Package-Pin	Device	Package-Pin
XQZU3EG	SFQC784	XQZU11EG	FFQC1156
XQZU4EG		XQZU11EG	FFQC1760
XQZU4EG	FBQB900	XQZU19EG	
XQZU6EG	FFQC900	XQZU19EG	FFQB1517
XQZU9EG			
XQZU9EG	FFQB1156		
XQZU9CG			

Table 2: **UltraScale+ Kintex® XQ Devices-Packages**

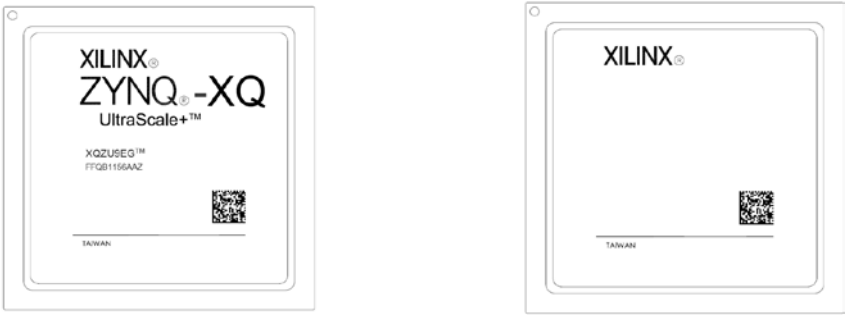
Device	Package-Pin	Device	Package-Pin
XQKU11P	FFQA1156	XQKU11P	FFQE1517

Table 3: **UltraScale+ Virtex® XQ Devices-Packages**

Device	Package-Pin	Device	Package-Pin
XQVU7P	FLQA2104	XQVU9P	FSQD2104
XQVU7P	FLQB2104	XQVU13P	FLQA2577
XQVU9P			
XQVU9P	FLQC2104		

Traceability

Affected devices are identified by the following package top marking as shown in Figure 1 below.



Current Marking

New Mark Simplification

Figure 1: Product Marking

Response

No response is required.

Important Notice: Xilinx Customer Notifications (XCNs, XDNs, and Quality Alerts) can be delivered via e-mail alerts sent by the Support website (https://www.xilinx.com/support). Register today and personalize your "Documentation and Design Advisory Alerts" area to include Customer Notifications. Xilinx Support provides many benefits, including the ability to receive alerts for new and updated information about specific products, as well as alerts for other publications such as data sheets, errata, application notes, etc. For information on how to sign up, refer to Xilinx Answer Record 18683.

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
05/28/2018	1.0	Initial Release.

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